

74AUP1G17

Low-power Schmitt-trigger buffer

Rev. 01 — 26 July 2005

Product data sheet

1. General description

The 74AUP1G17 is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Schmitt-trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial Power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74AUP1G17 provides the single Schmitt-trigger buffer. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

2. Features

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
 - ◆ JESD8-12 (0.8 V to 1.3 V)
 - ◆ JESD8-11 (0.9 V to 1.65 V)
 - ◆ JESD8-7 (1.2 V to 1.95 V)
 - ◆ JESD8-5 (1.8 V to 2.7 V)
 - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114-C exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101-C exceeds 1000 V
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

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3. Quick reference data

Table 1: Quick reference data*GND = 0 V; T_{amb} = 25 °C; t_r = t_f ≤ 3 ns.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t _{PHL} , t _{PLH}	propagation delay A to Y	C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 0.8 V	-	19.0	-	ns
		C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 1.1 V to 1.3 V	2.9	5.7	11.7	ns
		C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 1.4 V to 1.6 V	2.5	4.2	7.2	ns
		C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 1.65 V to 1.95 V	2.2	3.6	5.9	ns
		C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 2.3 V to 2.7 V	2.0	3.0	4.8	ns
		C _L = 5 pF; R _L = 1 MΩ; V _{CC} = 3.0 V to 3.6 V	1.9	2.8	4.3	ns
C _i	input capacitance		-	0.8	-	pF
C _{PD}	power dissipation capacitance	V _{CC} = 1.8 V; f = 10 MHz V _{CC} = 3.3 V; f = 10 MHz	[1][2] -	4.5	-	pF
		[1][2] -	6.0	-	pF	

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;f_o = output frequency in MHz;C_L = output load capacitance in pF;V_{CC} = supply voltage in V;

N = number of inputs switching;

Σ(C_L × V_{CC}² × f_o) = sum of the outputs.[2] The condition is V_I = GND to V_{CC}.

4. Ordering information

Table 2: Ordering information

Type number	Package				Version
	Temperature range	Name	Description	Version	
74AUP1G17GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm		SOT353-1
74AUP1G17GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm		SOT886

5. Marking

Table 3: Marking

Type number	Marking code
74AUP1G17GW	pJ
74AUP1G17GM	pJ

6. Functional diagram

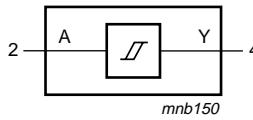


Fig 1. Logic symbol

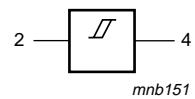


Fig 2. IEC logic symbol

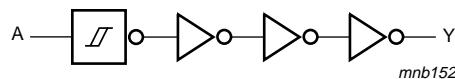


Fig 3. Logic diagram

7. Pinning information

7.1 Pinning

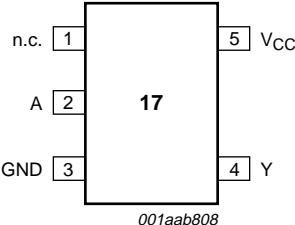


Fig 4. Pin configuration SOT353-1 (TSSOP5)

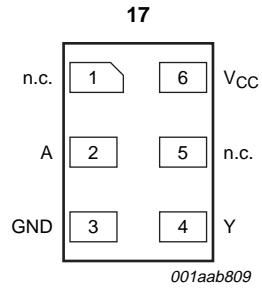


Fig 5. Pin configuration SOT886 (XSON6)

7.2 Pin description

Table 4: Pin description

Symbol	Pin		Description
	TSSOP5	XSON6	
n.c.	1	1	not connected
A	2	2	data input A
GND	3	3	ground (0 V)
Y	4	4	data output Y
n.c.	-	5	not connected
V _{CC}	5	6	supply voltage

8. Functional description

8.1 Function table

Table 5: Function table [1]

Input	Output
A	Y
L	L
H	H

[1] H = HIGH voltage level;
L = LOW voltage level.

9. Limiting values

Table 6: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-	-50	mA
V _I	input voltage		[1]	-0.5	+4.6
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage	active mode	[1]	-0.5	V _{CC} + 0.5 V
		Power-down mode	[1]	-0.5	+4.6 V
I _O	output current	V _O = 0 V to V _{CC}	-	±20	mA
I _{CC}	quiescent supply current		-	+50	mA
I _{GND}	ground current		-	-50	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	[2]	-	250 mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

For XSON6 packages: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

10. Recommended operating conditions

Table 7: Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		0.8	3.6	V
V _I	input voltage		0	3.6	V
V _O	output voltage	active mode	0	V _{CC}	V
		Power-down mode; V _{CC} = 0 V	0	3.6	V
T _{amb}	ambient temperature		-40	+125	°C

11. Static characteristics

Table 8: Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{OH}	HIGH-state output voltage	V _I = V _{IH} or V _{IL} I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V I _O = -1.1 mA; V _{CC} = 1.1 V I _O = -1.7 mA; V _{CC} = 1.4 V I _O = -1.9 mA; V _{CC} = 1.65 V I _O = -2.3 mA; V _{CC} = 2.3 V I _O = -3.1 mA; V _{CC} = 2.3 V I _O = -2.7 mA; V _{CC} = 3.0 V I _O = -4.0 mA; V _{CC} = 3.0 V	V _{CC} - 0.1	-	-	V
V _{OL}	LOW-state output voltage	V _I = V _{IH} or V _{IL} I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V I _O = 1.1 mA; V _{CC} = 1.1 V I _O = 1.7 mA; V _{CC} = 1.4 V I _O = 1.9 mA; V _{CC} = 1.65 V I _O = 2.3 mA; V _{CC} = 2.3 V I _O = 3.1 mA; V _{CC} = 2.3 V I _O = 2.7 mA; V _{CC} = 3.0 V I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.1	V
I _{LI}	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.1	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.2	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.2	µA
I _{CC}	quiescent supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.5	µA
ΔI _{CC}	additional quiescent supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	40	µA
C _i	input capacitance	V _I = GND or V _{CC} ; V _{CC} = 0 V to 3.6 V	-	0.8	-	pF
C _o	output capacitance	V _O = GND; V _{CC} = 0 V	-	1.7	-	pF

Table 8: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +85 °C						
V _{OH}	HIGH-state output voltage	V _I = V _{IH} or V _{IL} I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V I _O = -1.1 mA; V _{CC} = 1.1 V I _O = -1.7 mA; V _{CC} = 1.4 V I _O = -1.9 mA; V _{CC} = 1.65 V I _O = -2.3 mA; V _{CC} = 2.3 V I _O = -3.1 mA; V _{CC} = 2.3 V I _O = -2.7 mA; V _{CC} = 3.0 V I _O = -4.0 mA; V _{CC} = 3.0 V	V _{CC} - 0.1	-	-	V
V _{OL}	LOW-state output voltage	V _I = V _{IH} or V _{IL} I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V I _O = 1.1 mA; V _{CC} = 1.1 V I _O = 1.7 mA; V _{CC} = 1.4 V I _O = 1.9 mA; V _{CC} = 1.65 V I _O = 2.3 mA; V _{CC} = 2.3 V I _O = 3.1 mA; V _{CC} = 2.3 V I _O = 2.7 mA; V _{CC} = 3.0 V I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.1	V
I _{LI}	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.5	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.5	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.6	µA
I _{CC}	quiescent supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.9	µA
ΔI _{CC}	additional quiescent supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	50	µA

Table 8: Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{OH}	HIGH-state output voltage	V _I = V _{IH} or V _{IL} I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V I _O = -1.1 mA; V _{CC} = 1.1 V I _O = -1.7 mA; V _{CC} = 1.4 V I _O = -1.9 mA; V _{CC} = 1.65 V I _O = -2.3 mA; V _{CC} = 2.3 V I _O = -3.1 mA; V _{CC} = 2.3 V I _O = -2.7 mA; V _{CC} = 3.0 V I _O = -4.0 mA; V _{CC} = 3.0 V	V _{CC} - 0.11	-	-	V
V _{OL}	LOW-state output voltage	V _I = V _{IH} or V _{IL} I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V I _O = 1.1 mA; V _{CC} = 1.1 V I _O = 1.7 mA; V _{CC} = 1.4 V I _O = 1.9 mA; V _{CC} = 1.65 V I _O = 2.3 mA; V _{CC} = 2.3 V I _O = 3.1 mA; V _{CC} = 2.3 V I _O = 2.7 mA; V _{CC} = 3.0 V I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.11	V
I _{LI}	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.75	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.75	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.75	µA
I _{CC}	quiescent supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	1.4	µA
ΔI _{CC}	additional quiescent supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	75	µA

12. Dynamic characteristics

Table 9: Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#)

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
T_{amb} = 25 °C; C_L = 5 pF						
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6				
		V _{CC} = 0.8 V	-	19.0	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.9	5.7	11.7	ns
		V _{CC} = 1.4 V to 1.6 V	2.5	4.2	7.2	ns
		V _{CC} = 1.65 V to 1.95 V	2.2	3.6	5.9	ns
		V _{CC} = 2.3 V to 2.7 V	2.0	3.0	4.8	ns
		V _{CC} = 3.0 V to 3.6 V	1.9	2.8	4.3	ns
T_{amb} = 25 °C; C_L = 10 pF						
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6				
		V _{CC} = 0.8 V	-	22.9	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.4	6.6	13.5	ns
		V _{CC} = 1.4 V to 1.6 V	2.9	4.9	8.3	ns
		V _{CC} = 1.65 V to 1.95 V	2.6	4.2	6.7	ns
		V _{CC} = 2.3 V to 2.7 V	2.4	3.6	5.5	ns
		V _{CC} = 3.0 V to 3.6 V	2.3	3.3	4.9	ns
T_{amb} = 25 °C; C_L = 15 pF						
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6				
		V _{CC} = 0.8 V	-	26.4	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.8	7.4	14.8	ns
		V _{CC} = 1.4 V to 1.6 V	3.3	5.4	9.3	ns
		V _{CC} = 1.65 V to 1.95 V	3.0	4.7	7.5	ns
		V _{CC} = 2.3 V to 2.7 V	2.8	4.0	6.1	ns
		V _{CC} = 3.0 V to 3.6 V	2.7	3.8	5.4	ns
T_{amb} = 25 °C; C_L = 30 pF						
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6				
		V _{CC} = 0.8 V	-	36.7	-	ns
		V _{CC} = 1.1 V to 1.3 V	5.0	9.6	18.1	ns
		V _{CC} = 1.4 V to 1.6 V	4.2	7.0	12.2	ns
		V _{CC} = 1.65 V to 1.95 V	3.9	6.0	9.7	ns
		V _{CC} = 2.3 V to 2.7 V	3.6	5.1	7.8	ns
		V _{CC} = 3.0 V to 3.6 V	3.5	4.8	6.7	ns

Table 9: Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#)

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
T_{amb} = 25 °C						
C _{PD}	power dissipation capacitance	f = 10 MHz	[2][3]			
		V _{CC} = 0.8 V	-	3.4	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	3.9	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	4.2	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	4.5	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	5.4	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	6.0	-	pF

[1] All typical values are measured at nominal V_{CC}.[2] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;f_o = output frequency in MHz;C_L = output load capacitance in pF;V_{CC} = supply voltage in V;

N = number of inputs switching;

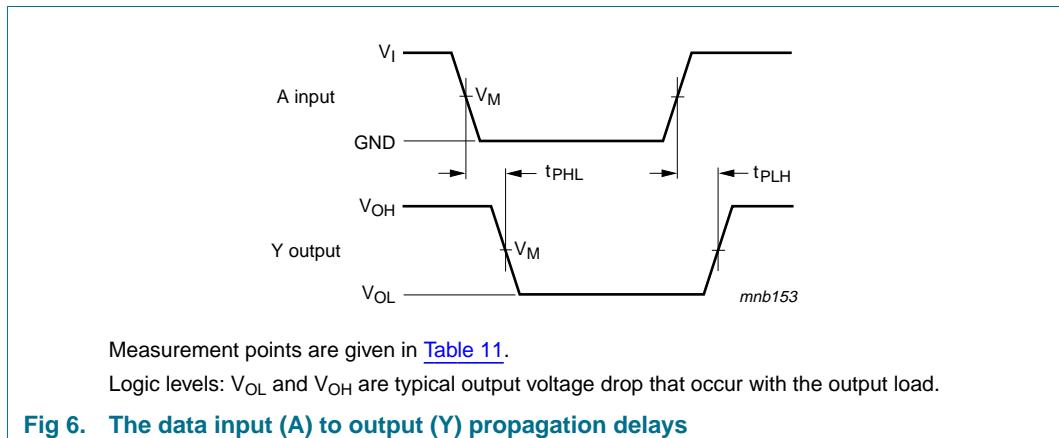
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.[3] The condition is V_I = GND to V_{CC}.**Table 10: Dynamic characteristics**Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#)

Symbol	Parameter	Conditions	−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Max	Min	Max	
C_L = 5 pF							
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6					
		V _{CC} = 1.1 V to 1.3 V	2.7	13.0	2.7	14.3	ns
		V _{CC} = 1.4 V to 1.6 V	2.3	8.4	2.3	9.3	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	7.0	2.0	7.7	ns
		V _{CC} = 2.3 V to 2.7 V	1.8	5.6	1.8	6.2	ns
		V _{CC} = 3.0 V to 3.6 V	1.7	5.0	1.7	5.5	ns
C_L = 10 pF							
t _{PHL} , t _{PLH}	propagation delay A to Y	see Figure 6					
		V _{CC} = 1.1 V to 1.3 V	3.1	14.9	3.1	16.4	ns
		V _{CC} = 1.4 V to 1.6 V	2.6	9.6	2.6	10.6	ns
		V _{CC} = 1.65 V to 1.95 V	2.4	7.9	2.4	8.7	ns
		V _{CC} = 2.3 V to 2.7 V	2.2	6.4	2.2	7.1	ns
		V _{CC} = 3.0 V to 3.6 V	2.2	5.7	2.2	6.3	ns

Table 10: Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#)

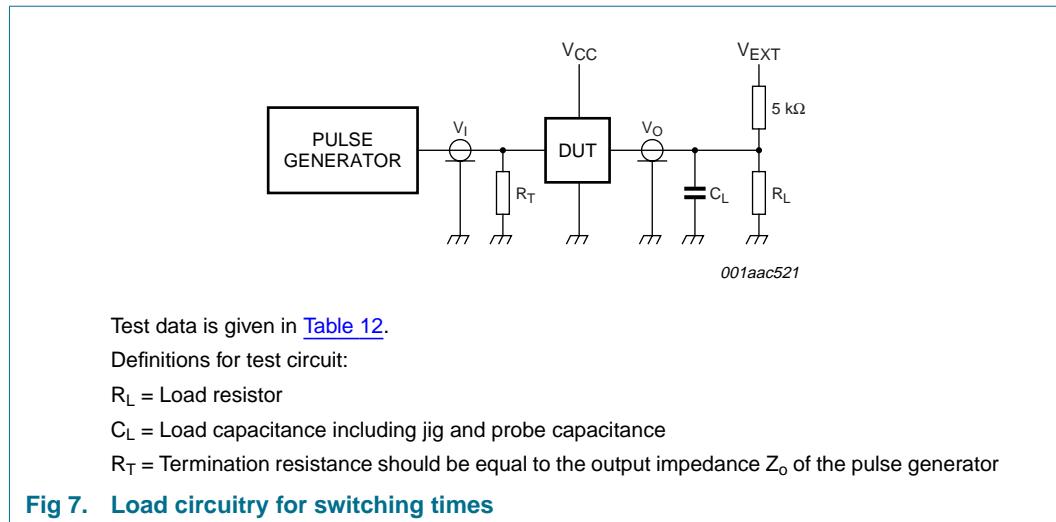
Symbol	Parameter	Conditions	−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Max	Min	Max	
$C_L = 15 \text{ pF}$							
t_{PHL}, t_{PLH}	propagation delay A to Y	see Figure 6					
			$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	3.5	16.7	3.5	18.4 ns
			$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	2.9	10.9	2.9	12.0 ns
			$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	2.7	8.8	2.7	9.7 ns
			$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	2.5	7.2	2.5	8.0 ns
			$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.5	6.2	2.5	6.9 ns
$C_L = 30 \text{ pF}$							
t_{PHL}, t_{PLH}	propagation delay A to Y	see Figure 6					
			$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	4.5	19.8	4.5	21.8 ns
			$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	3.8	14.4	3.8	15.9 ns
			$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	3.5	11.6	3.5	12.8 ns
			$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	3.3	9.3	3.3	10.3 ns
			$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	3.3	7.7	3.3	8.5 ns

13. Waveforms

**Table 11: Measurement points**

Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$

0.8 V to 3.6 V $0.5 \times V_{CC}$ $0.5 \times V_{CC}$ V_{CC} $\leq 3.0 \text{ ns}$

**Table 12: Test data**

Supply voltage	Load		V_{EXT}		
V_{CC}	C_L	R_L [1]	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V_{CC}

[1] For measuring enable and disable times $R_L = 5 \text{ k}\Omega$, for measuring propagation delays, setup and hold times and pulse width $R_L = 1 \text{ M}\Omega$.

14. Transfer characteristics

Table 13: Transfer characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = 25^\circ\text{C}$						
$V_{(th)LH}$	positive-going threshold voltage	see Figure 8 and Figure 9				
		$V_{CC} = 0.8 \text{ V}$	0.30	-	0.60	V
		$V_{CC} = 1.1 \text{ V}$	0.53	-	0.90	V
		$V_{CC} = 1.4 \text{ V}$	0.74	-	1.11	V
		$V_{CC} = 1.65 \text{ V}$	0.91	-	1.29	V
		$V_{CC} = 2.3 \text{ V}$	1.37	-	1.77	V
		$V_{CC} = 3.0 \text{ V}$	1.88	-	2.29	V
$V_{(th)HL}$	negative-going threshold voltage	see Figure 8 and Figure 9				
		$V_{CC} = 0.8 \text{ V}$	0.10	-	0.60	V
		$V_{CC} = 1.1 \text{ V}$	0.26	-	0.65	V
		$V_{CC} = 1.4 \text{ V}$	0.39	-	0.75	V
		$V_{CC} = 1.65 \text{ V}$	0.47	-	0.84	V
		$V_{CC} = 2.3 \text{ V}$	0.69	-	1.04	V
		$V_{CC} = 3.0 \text{ V}$	0.88	-	1.24	V

Table 13: Transfer characteristics ...continued
Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{hys}	hysteresis voltage $(V_{(\text{th})\text{LH}} - V_{(\text{th})\text{HL}})$	see Figure 8 , Figure 9 , Figure 10 and Figure 11				
		$V_{\text{CC}} = 0.8 \text{ V}$	0.07	-	0.50	V
		$V_{\text{CC}} = 1.1 \text{ V}$	0.08	-	0.46	V
		$V_{\text{CC}} = 1.4 \text{ V}$	0.18	-	0.56	V
		$V_{\text{CC}} = 1.65 \text{ V}$	0.27	-	0.66	V
		$V_{\text{CC}} = 2.3 \text{ V}$	0.53	-	0.92	V
		$V_{\text{CC}} = 3.0 \text{ V}$	0.79	-	1.31	V
$T_{\text{amb}} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$						
$V_{(\text{th})\text{LH}}$	positive-going threshold voltage	see Figure 8 and Figure 9				
		$V_{\text{CC}} = 0.8 \text{ V}$	0.30	-	0.60	V
		$V_{\text{CC}} = 1.1 \text{ V}$	0.53	-	0.90	V
		$V_{\text{CC}} = 1.4 \text{ V}$	0.74	-	1.11	V
		$V_{\text{CC}} = 1.65 \text{ V}$	0.91	-	1.29	V
		$V_{\text{CC}} = 2.3 \text{ V}$	1.37	-	1.77	V
		$V_{\text{CC}} = 3.0 \text{ V}$	1.88	-	2.29	V
$V_{(\text{th})\text{HL}}$	negative-going threshold voltage	see Figure 8 and Figure 9				
		$V_{\text{CC}} = 0.8 \text{ V}$	0.10	-	0.60	V
		$V_{\text{CC}} = 1.1 \text{ V}$	0.26	-	0.65	V
		$V_{\text{CC}} = 1.4 \text{ V}$	0.39	-	0.75	V
		$V_{\text{CC}} = 1.65 \text{ V}$	0.47	-	0.84	V
		$V_{\text{CC}} = 2.3 \text{ V}$	0.69	-	1.04	V
		$V_{\text{CC}} = 3.0 \text{ V}$	0.88	-	1.24	V
V_{hys}	hysteresis voltage $(V_{(\text{th})\text{LH}} - V_{(\text{th})\text{HL}})$	see Figure 8 , Figure 9 , Figure 10 and Figure 11				
		$V_{\text{CC}} = 0.8 \text{ V}$	0.07	-	0.50	V
		$V_{\text{CC}} = 1.1 \text{ V}$	0.08	-	0.46	V
		$V_{\text{CC}} = 1.4 \text{ V}$	0.18	-	0.56	V
		$V_{\text{CC}} = 1.65 \text{ V}$	0.27	-	0.66	V
		$V_{\text{CC}} = 2.3 \text{ V}$	0.53	-	0.92	V
		$V_{\text{CC}} = 3.0 \text{ V}$	0.79	-	1.31	V
$T_{\text{amb}} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$						
$V_{(\text{th})\text{LH}}$	positive-going threshold voltage	see Figure 8 and Figure 9				
		$V_{\text{CC}} = 0.8 \text{ V}$	0.30	-	0.62	V
		$V_{\text{CC}} = 1.1 \text{ V}$	0.53	-	0.92	V
		$V_{\text{CC}} = 1.4 \text{ V}$	0.74	-	1.13	V
		$V_{\text{CC}} = 1.65 \text{ V}$	0.91	-	1.31	V
		$V_{\text{CC}} = 2.3 \text{ V}$	1.37	-	1.80	V
		$V_{\text{CC}} = 3.0 \text{ V}$	1.88	-	2.32	V

Table 13: Transfer characteristics ...continued
Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(th)HL}$	negative-going threshold voltage	see Figure 8 and Figure 9				
		$V_{CC} = 0.8 \text{ V}$	0.10	-	0.60	V
		$V_{CC} = 1.1 \text{ V}$	0.26	-	0.65	V
		$V_{CC} = 1.4 \text{ V}$	0.39	-	0.75	V
		$V_{CC} = 1.65 \text{ V}$	0.47	-	0.84	V
		$V_{CC} = 2.3 \text{ V}$	0.69	-	1.04	V
		$V_{CC} = 3.0 \text{ V}$	0.88	-	1.24	V
V_{hys}	hysteresis voltage ($V_{(th)LH} - V_{(th)HL}$)	see Figure 8 , Figure 9 , Figure 10 and Figure 11				
		$V_{CC} = 0.8 \text{ V}$	0.07	-	0.50	V
		$V_{CC} = 1.1 \text{ V}$	0.08	-	0.46	V
		$V_{CC} = 1.4 \text{ V}$	0.18	-	0.56	V
		$V_{CC} = 1.65 \text{ V}$	0.27	-	0.66	V
		$V_{CC} = 2.3 \text{ V}$	0.53	-	0.92	V
		$V_{CC} = 3.0 \text{ V}$	0.79	-	1.31	V

15. Waveforms transfer characteristics

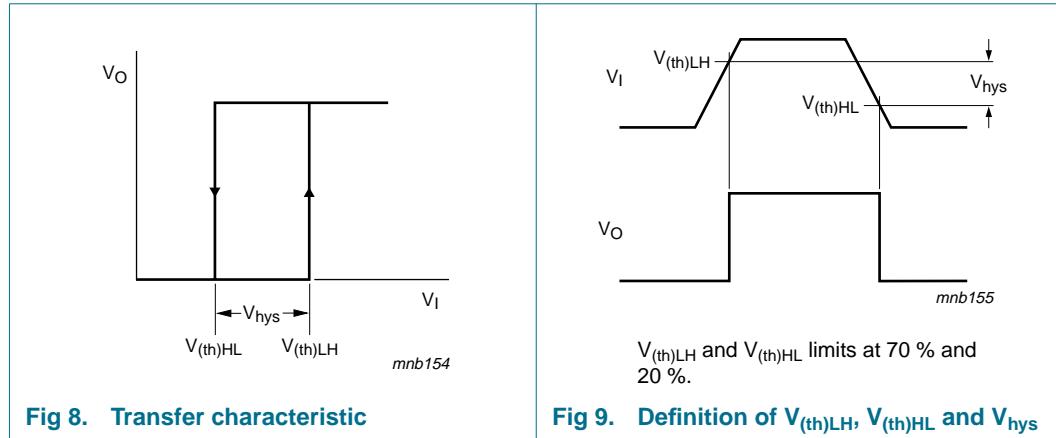


Fig 8. Transfer characteristic

Fig 9. Definition of $V_{(th)LH}$, $V_{(th)HL}$ and V_{hys}

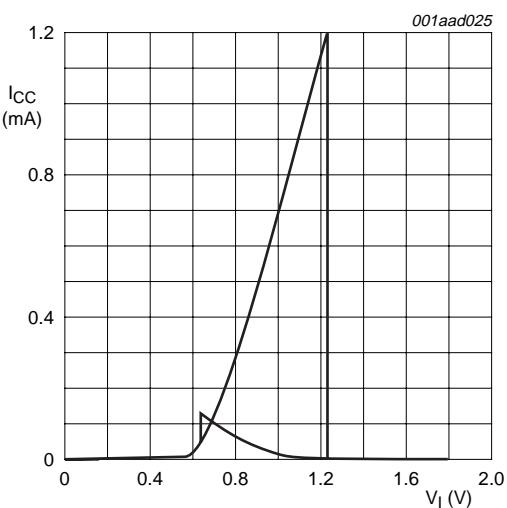


Fig 10. Typical transfer characteristics; $V_{CC} = 1.8 \text{ V}$

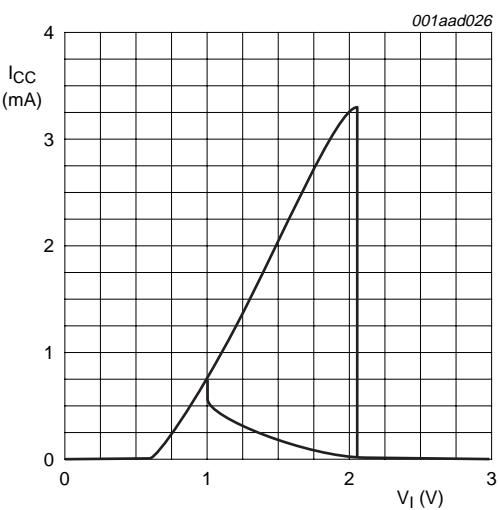


Fig 11. Typical transfer characteristics; $V_{CC} = 3.0 \text{ V}$

16. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{ad} = f_i \times (t_r \times I_{CC(AV)} + t_f \times I_{CC(AV)}) \times V_{CC} \text{ where:}$$

P_{ad} = additional power dissipation (μW);

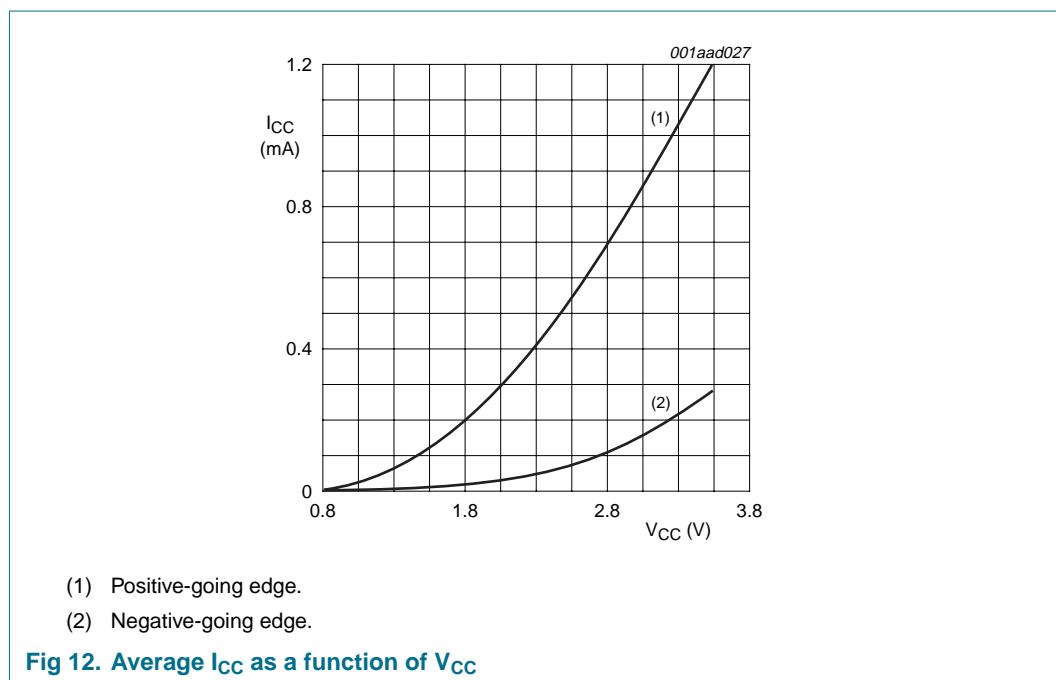
f_i = input frequency (MHz);

t_r = input rise time (ns); 10 % to 90 %;

t_f = input fall time (ns); 90 % to 10 %;

$I_{CC(AV)}$ = average additional supply current (μA).

Average I_{CC} differs with positive or negative input transitions, as shown in [Figure 12](#).



17. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

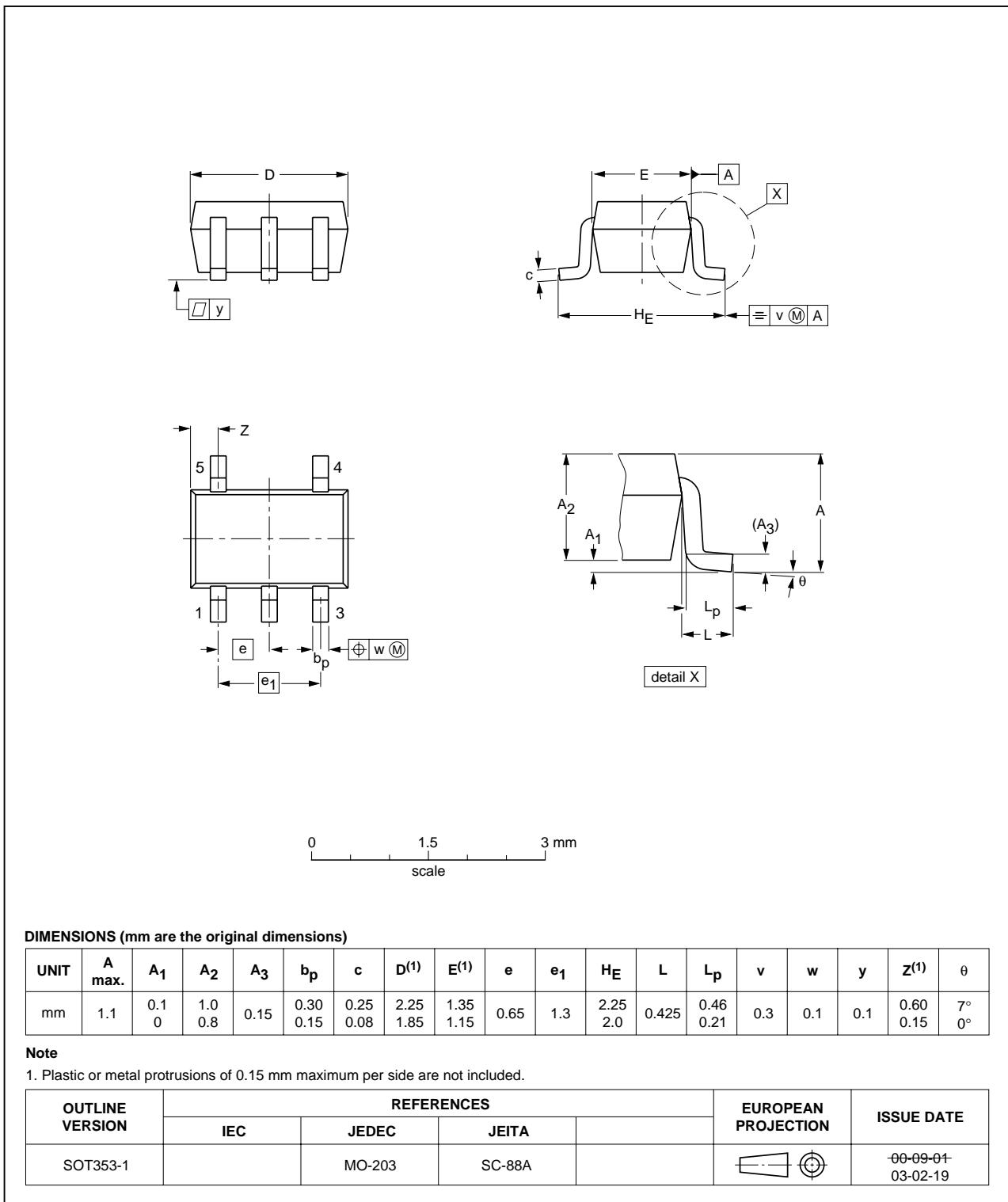
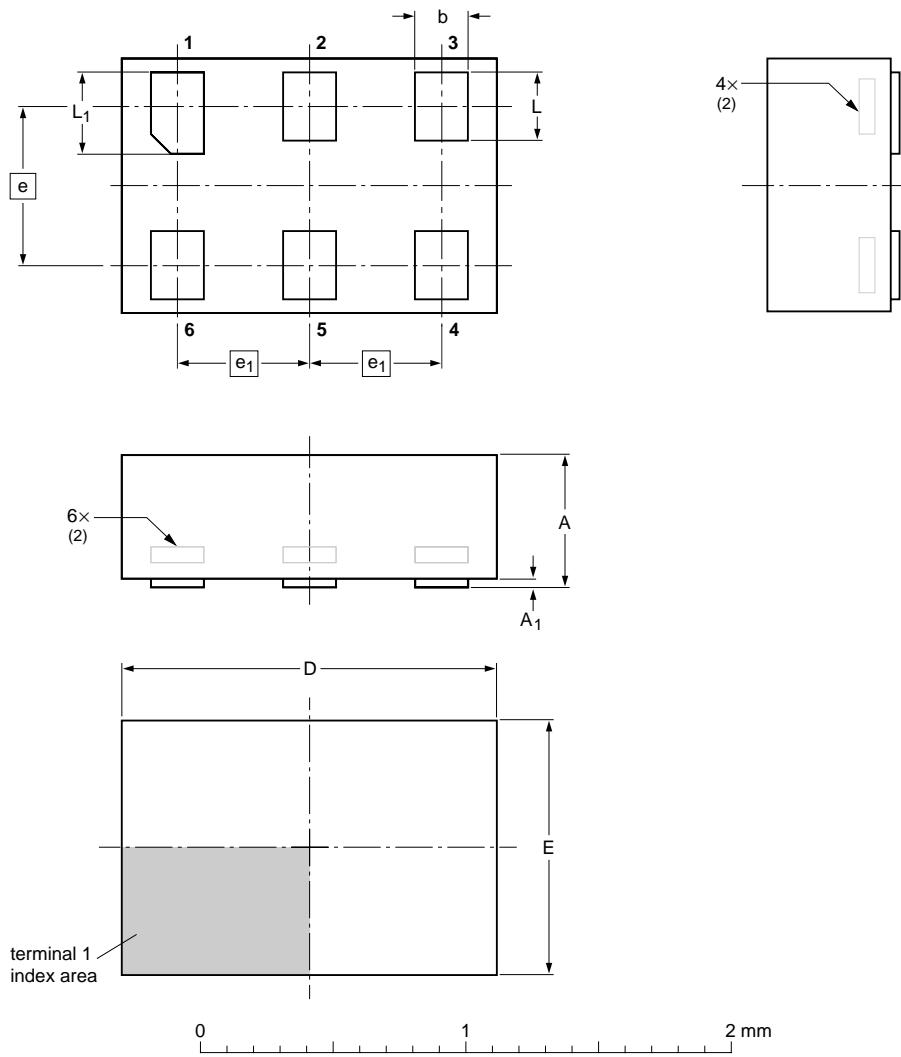


Fig 13. Package outline SOT353-1 (TSSOP5)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body $1 \times 1.45 \times 0.5$ mm

SOT886

**DIMENSIONS (mm are the original dimensions)**

UNIT	$A^{(1)}$ max	A_1 max	b	D	E	e	e_1	L	L_1
mm	0.5	0.04	0.25 0.17	1.5 1.4	1.05 0.95	0.6	0.5	0.35 0.27	0.40 0.32

Notes

1. Including plating thickness.
2. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT886		MO-252				-04-07-15 04-07-22

Fig 14. Package outline SOT886 (XSON6)



18. Abbreviations

Table 14: Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
TTL	Transistor Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
CDM	Charged Device Model

19. Revision history

Table 15: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
74AUP1G17_1	20050726	Product data sheet	-	9397 750 14677	-

20. Data sheet status

Level	Data sheet status [1]	Product status [2][3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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